



Material Content Data Sheet



Halogen-Free

Sales Product Name IPSA70R1K4CE

Issued

11. April 2021

MA# MA001809726

Package PG-TO251-3-347

Weight*

301.74 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.898	0.63	0.63	6289	6289
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		146	
	non noble metal	iron	7439-89-6	0.146	0.05		485	
	non noble metal	copper	7440-50-8	146.214	48.47	48.53	484566	485197
wire	non noble metal	aluminium	7429-90-5	0.455	0.15	0.15	1508	1508
encapsulation	organic material	carbon black	1333-86-4	1.246	0.41		4130	
	plastics	epoxy resin	-	23.680	7.85		78479	
	inorganic material	silicondioxide	60676-86-0	99.706	33.04	41.30	330437	413046
leadfinish	non noble metal	tin	7440-31-5	3.774	1.25	1.25	12508	12508
solder	non noble metal	tin	7440-31-5	0.042	0.01		139	
	noble metal	silver	7440-22-4	0.052	0.02		173	
	non noble metal	lead	7439-92-1	1.999	0.66	0.69	6625	6937
heatspreader	inorganic material	phosphorus	7723-14-0	0.007			22	
	non noble metal	iron	7439-89-6	0.022	0.01		75	
	non noble metal	copper	7440-50-8	22.455	7.44	7.45	74418	74515
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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